# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**
[List multiple models if applicable.]

| HP ProBook 4340s/4341s Notebook PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Main battery, RTC battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Yes, AC Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers | No | 0
Components, parts and materials containing radioactive substances | No | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 T8 Trox screwdriver</td>
<td>T8</td>
</tr>
<tr>
<td>Description #2 Cross screwdriver</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 Nipper</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release Battery and Access Door
2. Release ODD Module and HDD Module
3. Release Keyboard Module
4. Disassemble U-case Ass’y from L case Ass’y (MB)
5. Disassemble Speaker R/L
6. Disassemble MB from L-case Ass’y
7. Disassemble Hinge Up from L-case Ass’y
8. Hinge Up Disassembly
9. Bezel Disassembly
10. LCD/ Hinge Module Disassembly

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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PSG instructions for this template are available at [EL-MF877-01](#)
1st Step: Release Battery and Access Door

1. Push battery knob inside to release battery
2. Push battery knob inside to release door after battery released
2nd Step: Release ODD Module and HDD Module

1. Loose one ODD screw, then push ODD module bracket to release
2. Loose 4 HDD screws, then pull HDD right to release
3rd Step: Release Keyboard Module

1. Loose 3 screws for keyboard, then push keyboard down (palm rest direction) and release keyboard mainbrane, then release keyboard keyboard Module (3 screws)
4th Step: Disassemble U-case Ass’y from L case Ass’y (MB)

1. Loosen 17 screws at bottom and 1 screw at top, then release audio FFC and power FFC
2. Disassemble U-case ass’y from L-case ass’y (MB)
4th Step: Disassemble U-case Ass’y from L case Ass’y (MB)
5th Step: Disassemble Speaker R/L

1. Loose 4 screws to disassemble speaker R/L
6th Step: Disassemble MB from L-case Ass’y

1. Release LVDS cable
2. Loose screw and take MB from L-case ass’y
7th Step: Disassemble Hinge Up from L-case Ass’y

1. Release 4 antenna cables from cable groove at bottom of L-case ass’y
7th Step: Disassemble Hinge Up from L-case Ass’y

2. Loose 3 hinge screws
3. Take hinge up from L-case ass’y
8th Step: Hinge Up Disassembly

1. Disassemble hinge cap L and hinge cap R from hinge up
9th Step: Bezel Disassembly

1. Loose 2 bezel plugs and screws to disassemble bezel
10th Step: LCD/ Hinge Module Disassembly

1. Loose 6 hinge screws
2. Release camera connector and take LCD/ hinge module from LCD cover ass’y